



Cooling of the Belle-II PXD detector

C. Marinas IFIC-Valencia

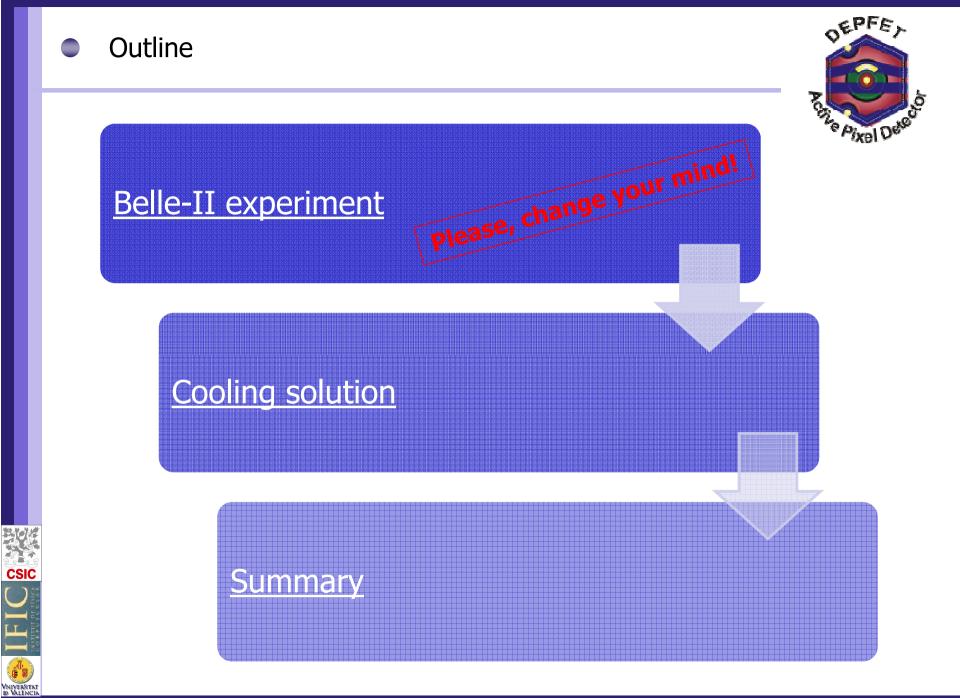


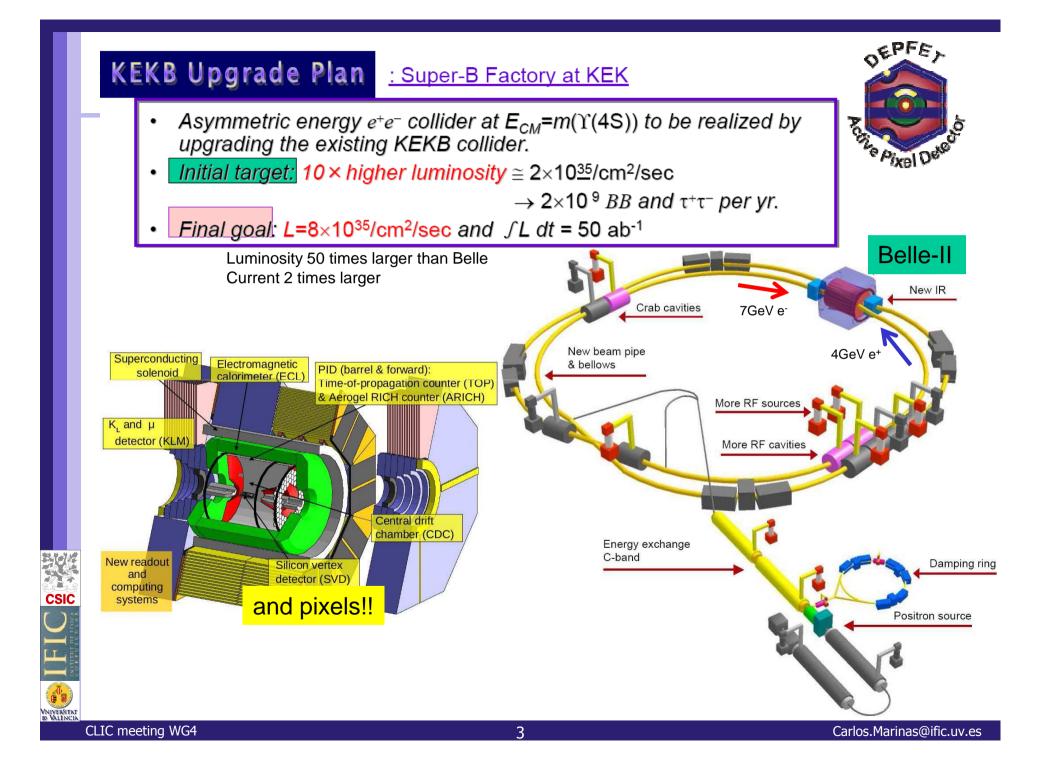
CLIC Meeting WG4 6.6.2010





CLIC meeting WG4







From ILC to Belle-II



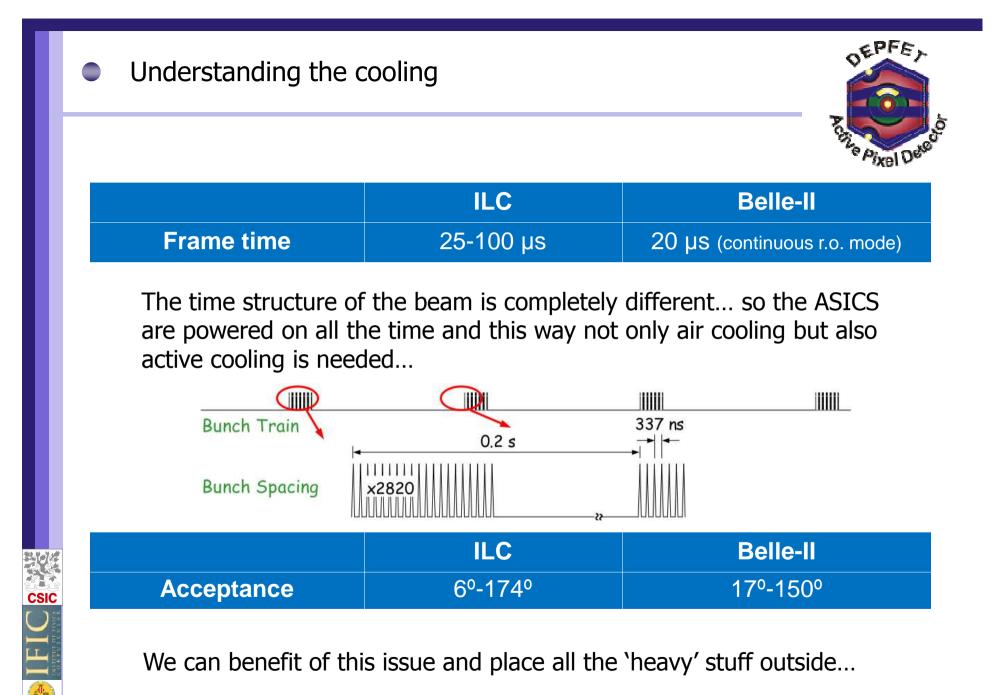
• Belle-II is more challenging rather than ILC in some points

	ILC	Belle-II
Occupancy	0.13 hits/µm²/s	0.4 hits/µm²/s
Radiation	< 100 krad/year	> 1Mrad/year
Duty cycle	1/200	1
Frame time	25-100 µs	20 μs (continuous r.o. mode)
Momentum range	All momenta	Low momentum (< 1 GeV)
Acceptance	6º-174º	17º-150º

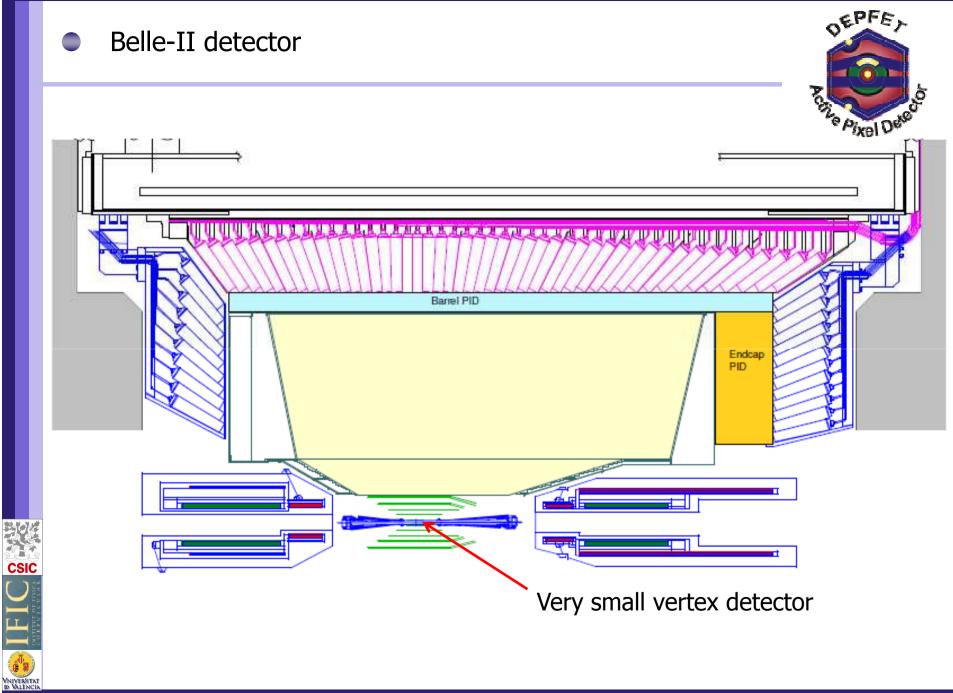
• ILC

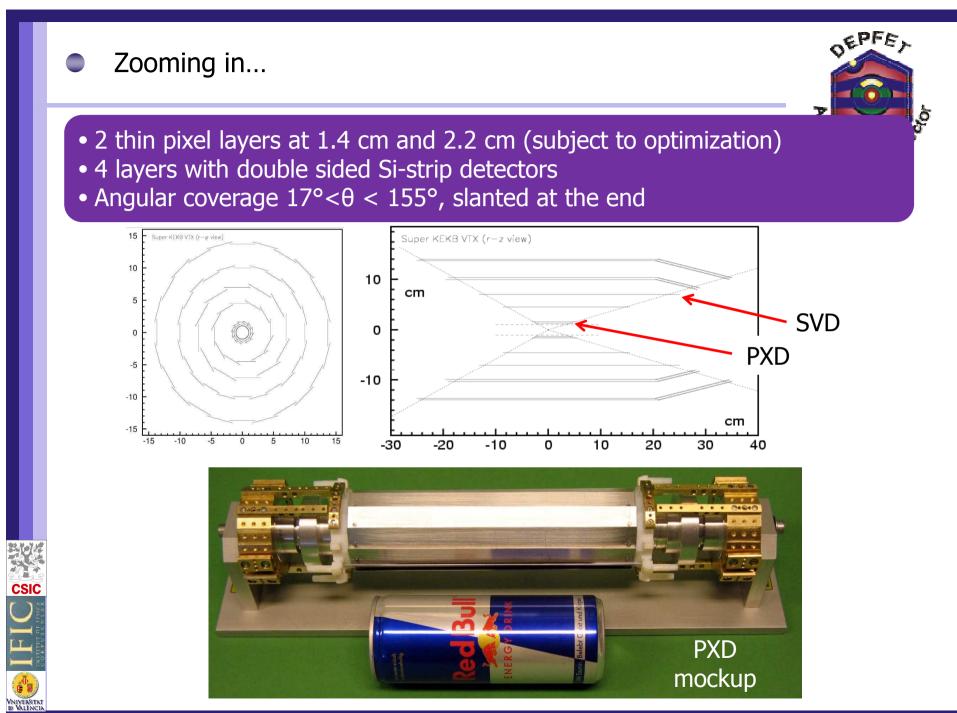
- > Excellent single point resolution (3-5 μ m) > Small pixel size 25 μ m²
- ➤ Low material budget (0.12%X₀/layer)
- Belle II

- > Modest spatial resolution (10 μ m) > Moderate pixel size (50 x 75 μ m²)
- > Few 100 MeV momenta \rightarrow Lowest possible material budget (0.15% X₀/layer)



CLIC meeting WG4

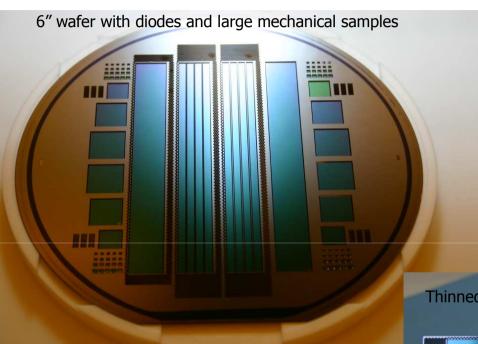




7







• The stiffness is provided by the frame itself

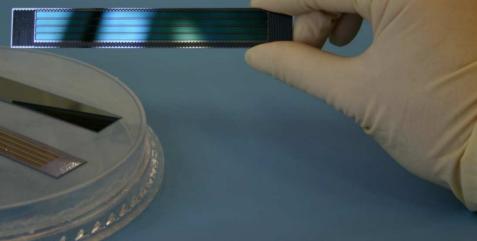
• No aditional support structure is required

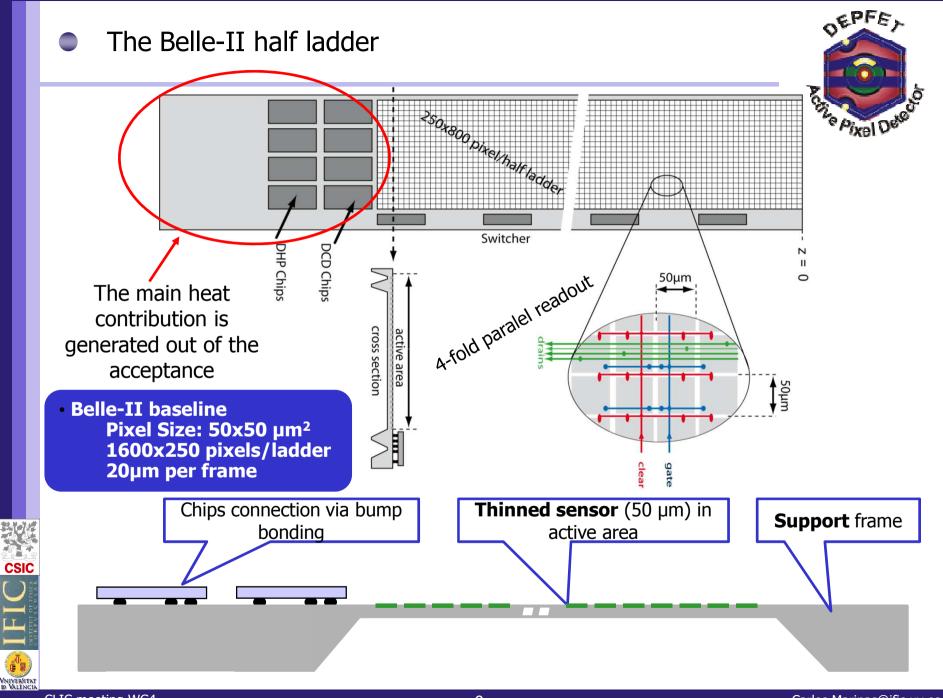
Thinned area: 10cm x 1.2 cm (ILC vertex detector dummy)

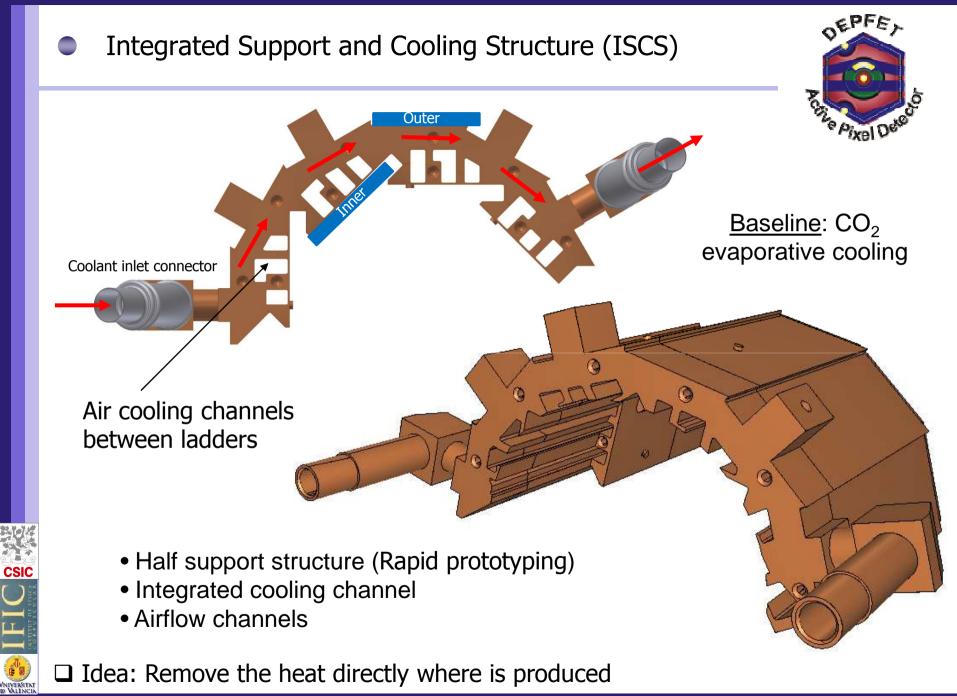
The material budget... a crucial issue!

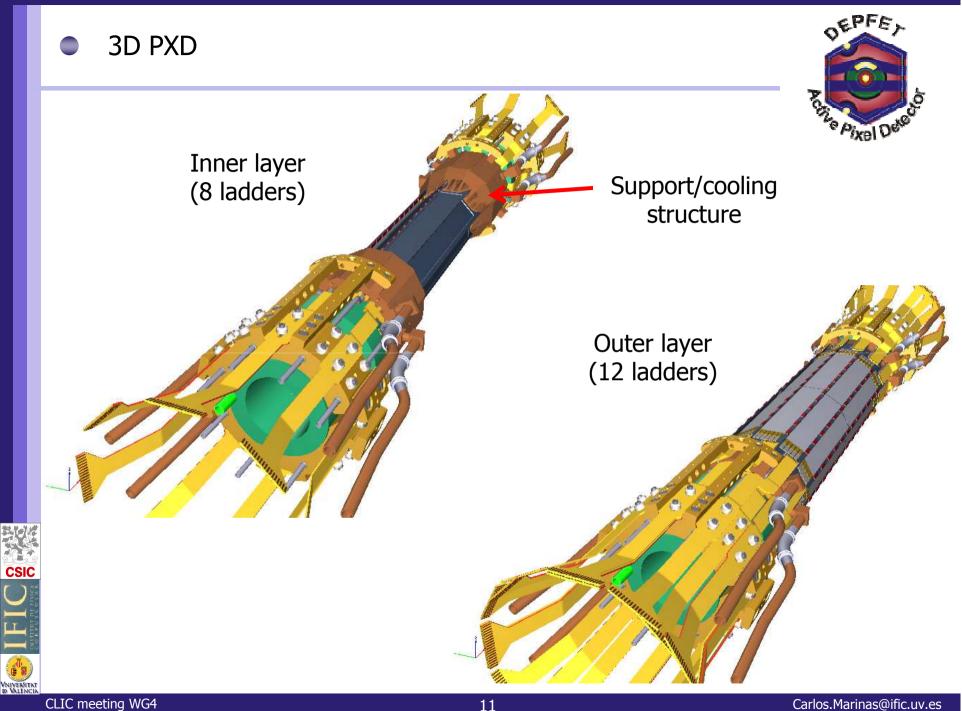
 \rightarrow Try to reduce the m.s. contribution

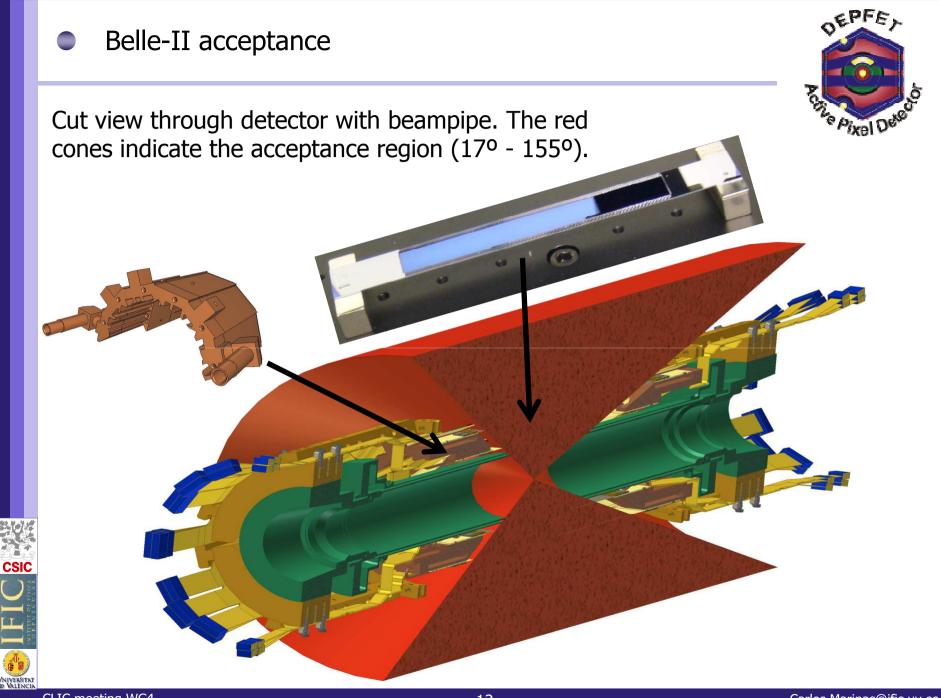
Sensor: Thinned down to 50µm
Balconies: Etched grooves

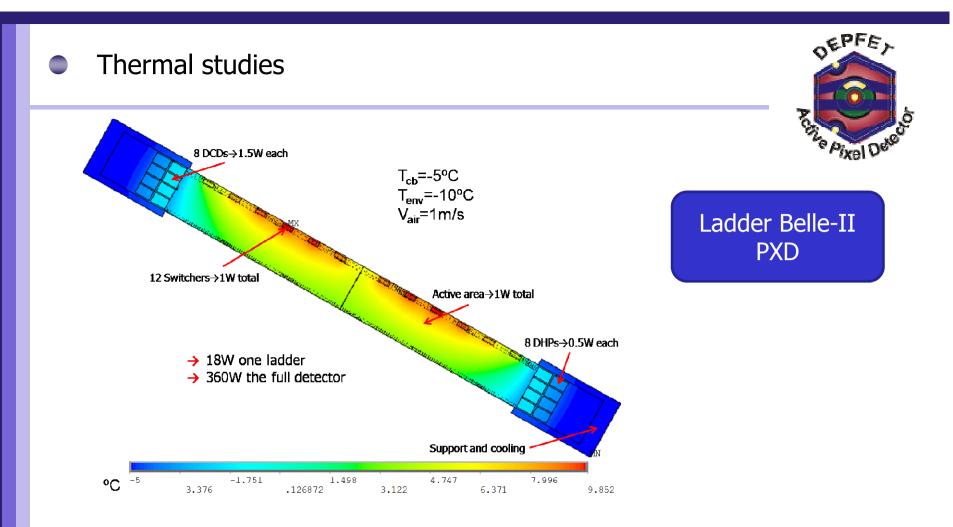










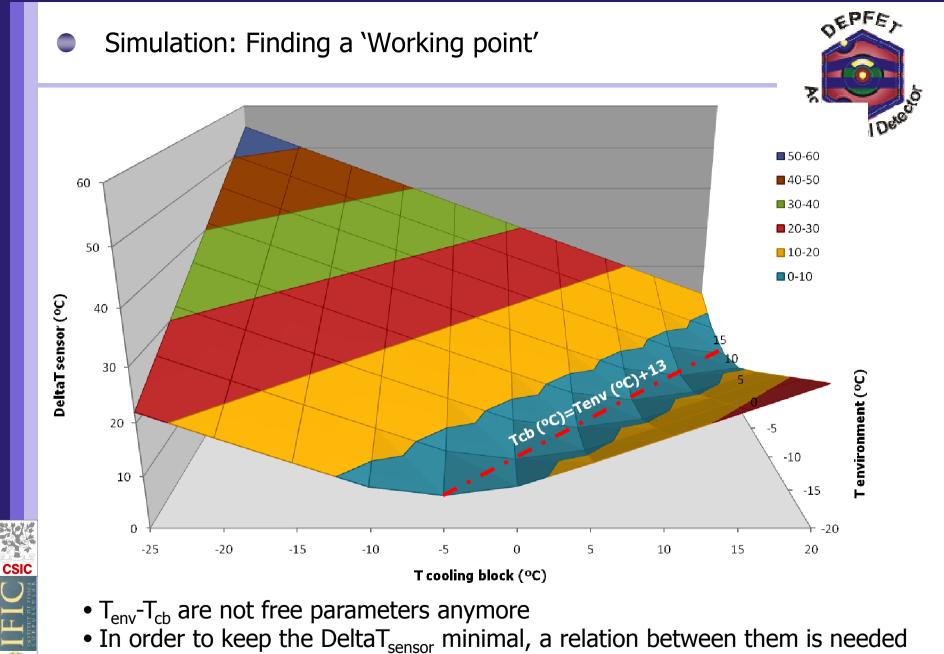


By means of thermal simulations (cross checked with measurements) we know that:

The end of stave has to be cooled by means of conduction (massive cooling structures at both ends; see previous slide)

The center of the ladder is an issue for the forced convection

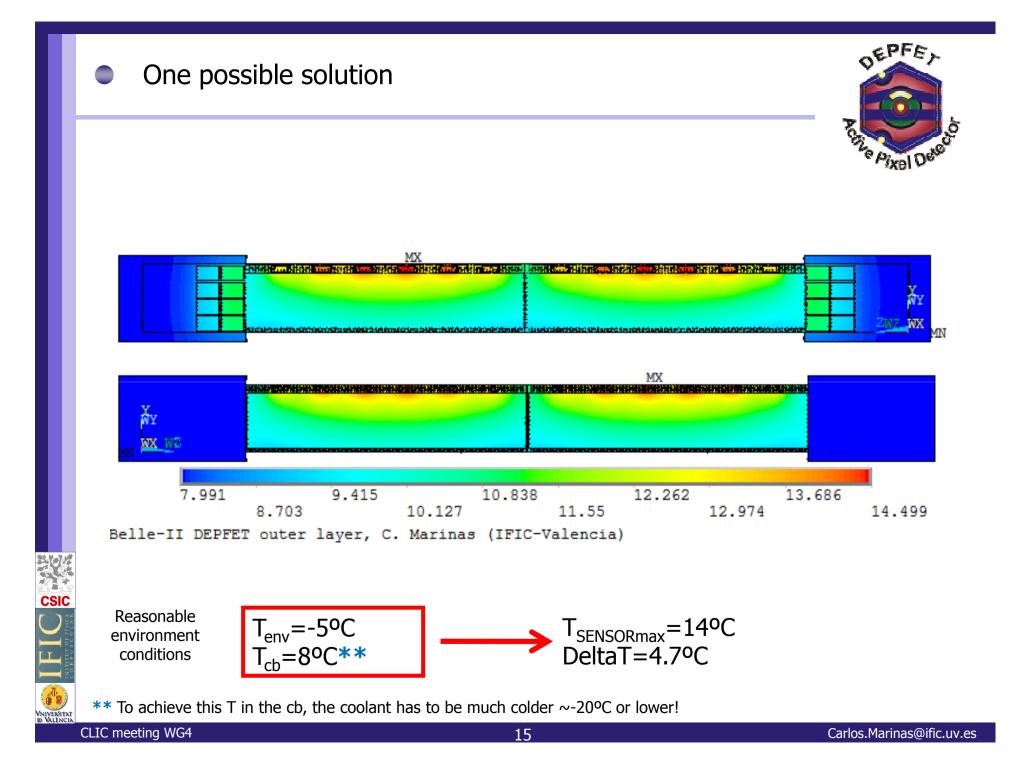
> The center of the ladder is an issue for the forced convection



• This relation depends on the sensor thickness!

CLIC meeting WG4

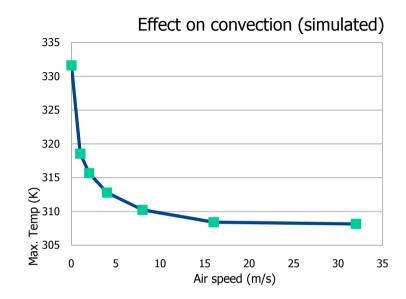
NIVERSITAT





Air speed effect





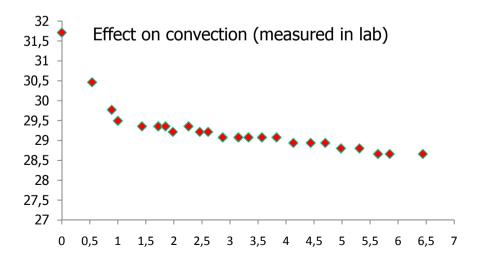
A big mass flow is not needed...

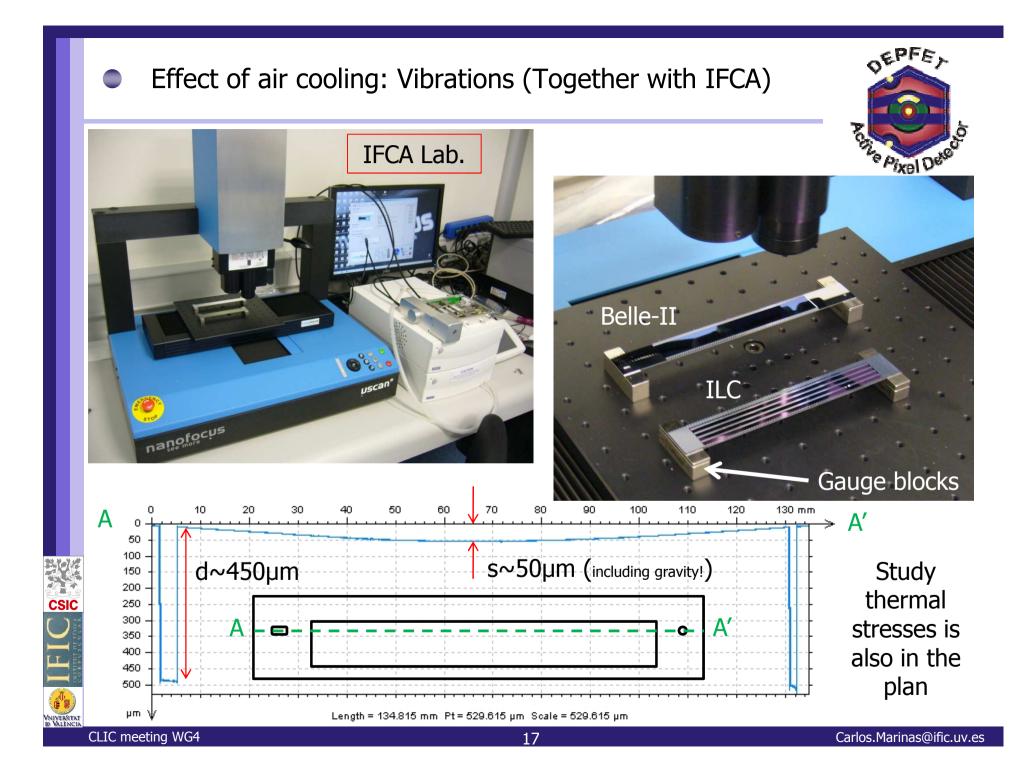
Just a small speed to move the heat out of the central part (~1m/s)

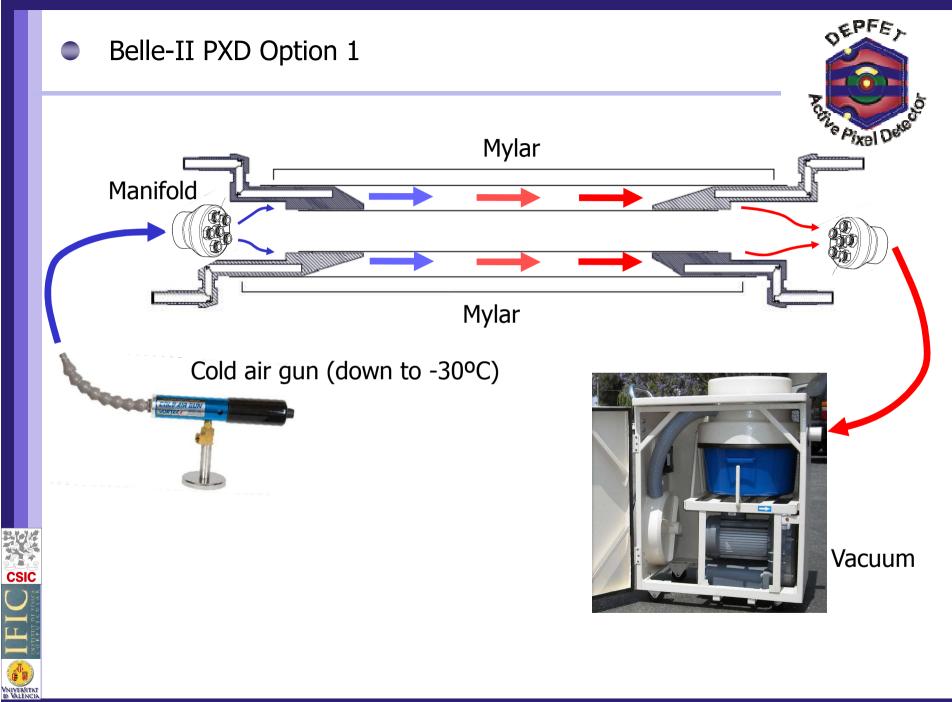
Air cooling solutions are on the way!

We obtain the same behaviour in both, simulations and measurements

The temperatures can not be compared because of different geometries

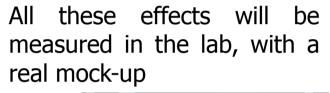


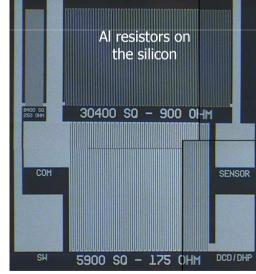














Simplified support structure for testing purposes

Holes for the cold air Ring for

Ring for the cooling pipe

• The beam pipe is missing in this drawing, but it will be there (with its own temperature $\sim 15^{\circ}$ C) in the final design

CLIC meeting WG4

CSIC

NIVERSITAT



AIDA project (Detector R&D)



□ In the near future, all these thermal and mechanical activities could be performed inside the AIDA project

<u>Aim</u>: Improve common infrastructures required for detector R&D, with trans-national access to beam tests and irradiation facilities \rightarrow **R&D in detectors**

User communities: SLHC (luminosity-upgraded LHC), future Linear Colliders (ILC and CLIC), future accelerator-driven neutrino facilities or future B-physics facilities (e.g. Super-B).

Groups involved: DESY, Oxford, CEA Saclay, Strasbourg, IFCA, IFIC

Budget 600.000 €





□ Belle-II detector is foreseen to be installed by the fall of 2013

- > This project boosted the DEPFET development
- \succ All the 'minor' details are being studied!

□ Because of the special features of the Belle-II...

- the cooling rely on:
 - \succ Conduction at both ends of the staves \rightarrow CO₂ evaporative cooling
 - \succ Convection in the center of the ladder \rightarrow Forced cold airflow To be measured in lab!
- from the mechanics:

 \succ The sensor is an all-silicon self support structure, with very low material budget

 \succ The detector rests on a heavy support/cooling structure outside of the acceptance

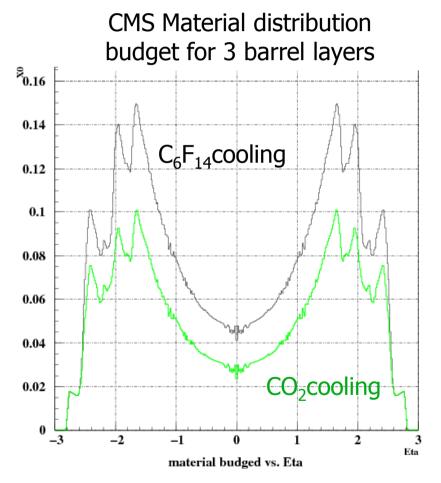


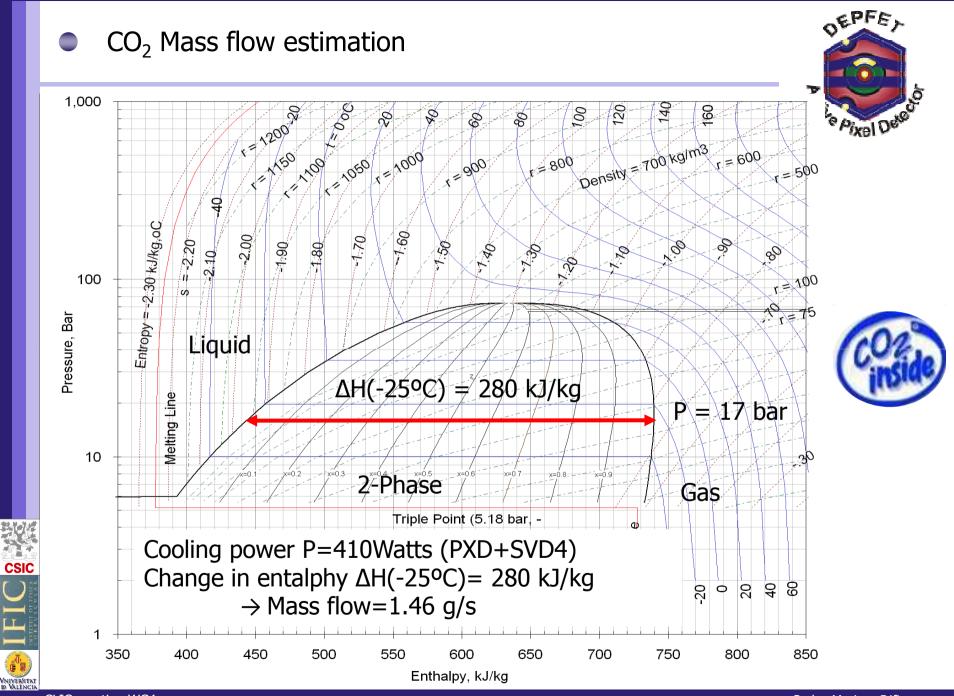
CLIC

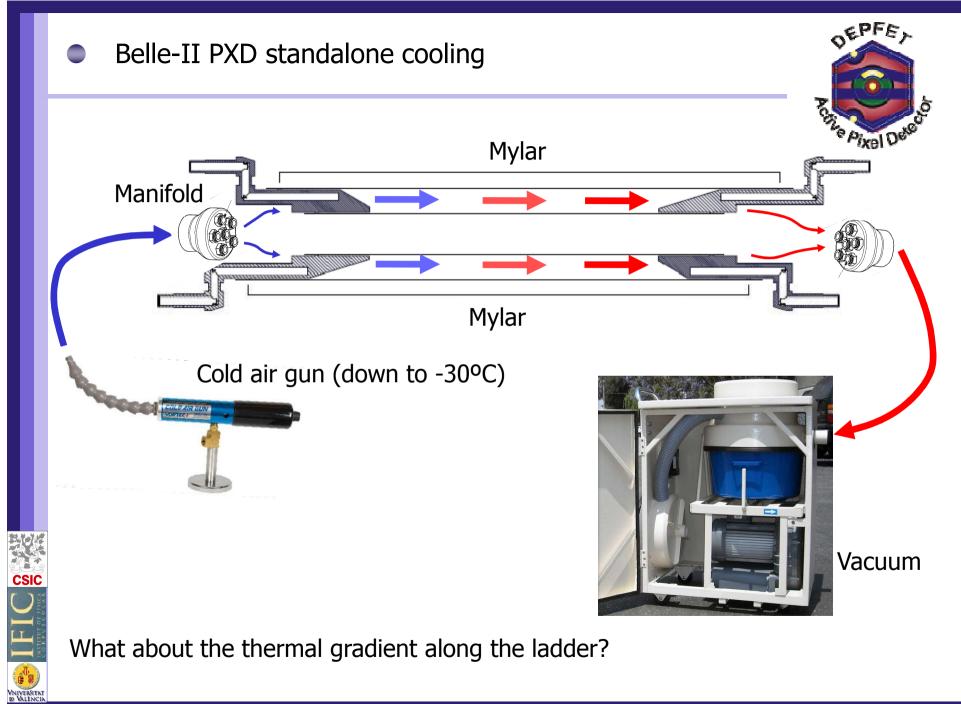




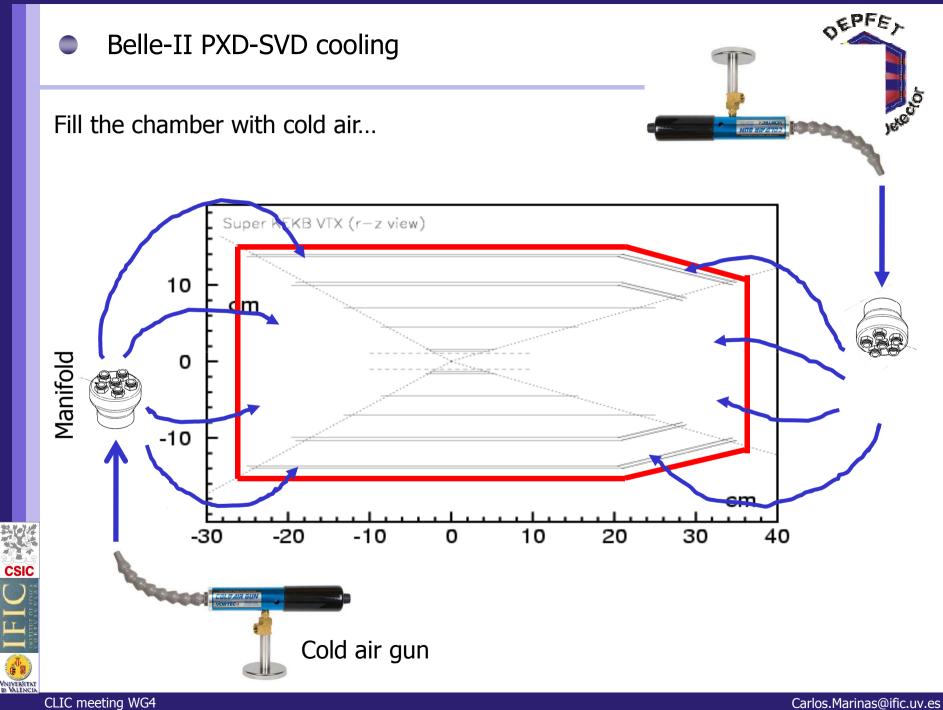
- Cooling loops (radius of 5mm) with very small pipes (outter radius ~1.3mm, wall thickness ~50µm)
- The material budget is reduced
- LHCb, AMS, CMS, ATLAS, industry
 → Growing interest in this coolant
 (CO₂)
- Low mass flow needed
- No corrosion
- Bigger engineering studies are required
- High pressures



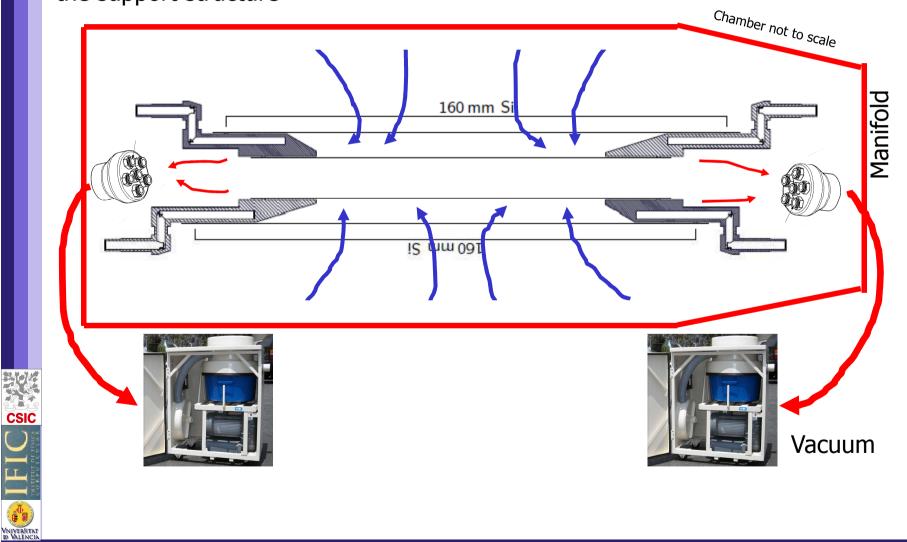




CLIC meeting WG4



And take the air out from both sides of the PXD, using the holes in the support structure



CLIC meeting WG4

OEPFET

2 Pixel Det

S S